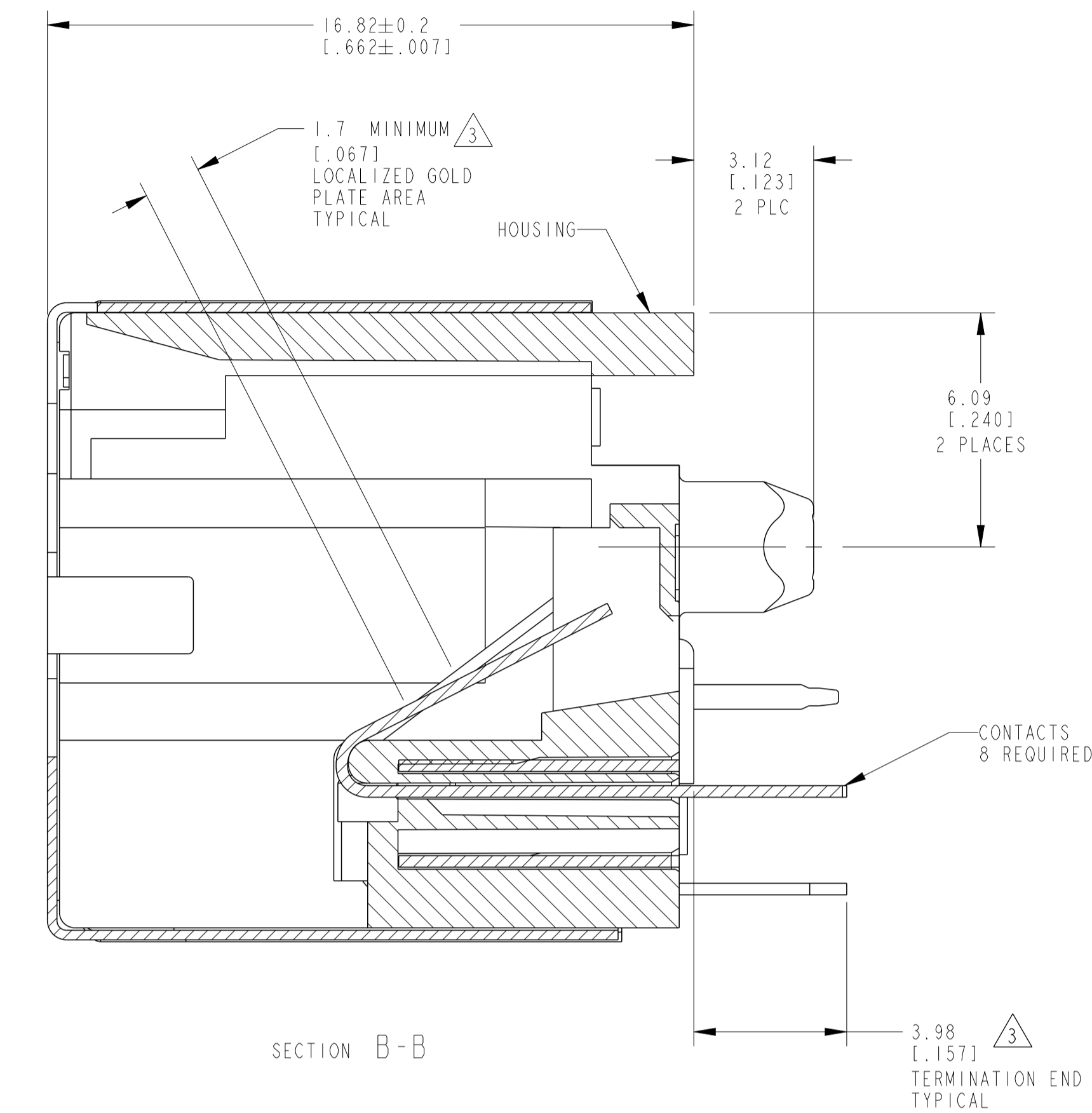
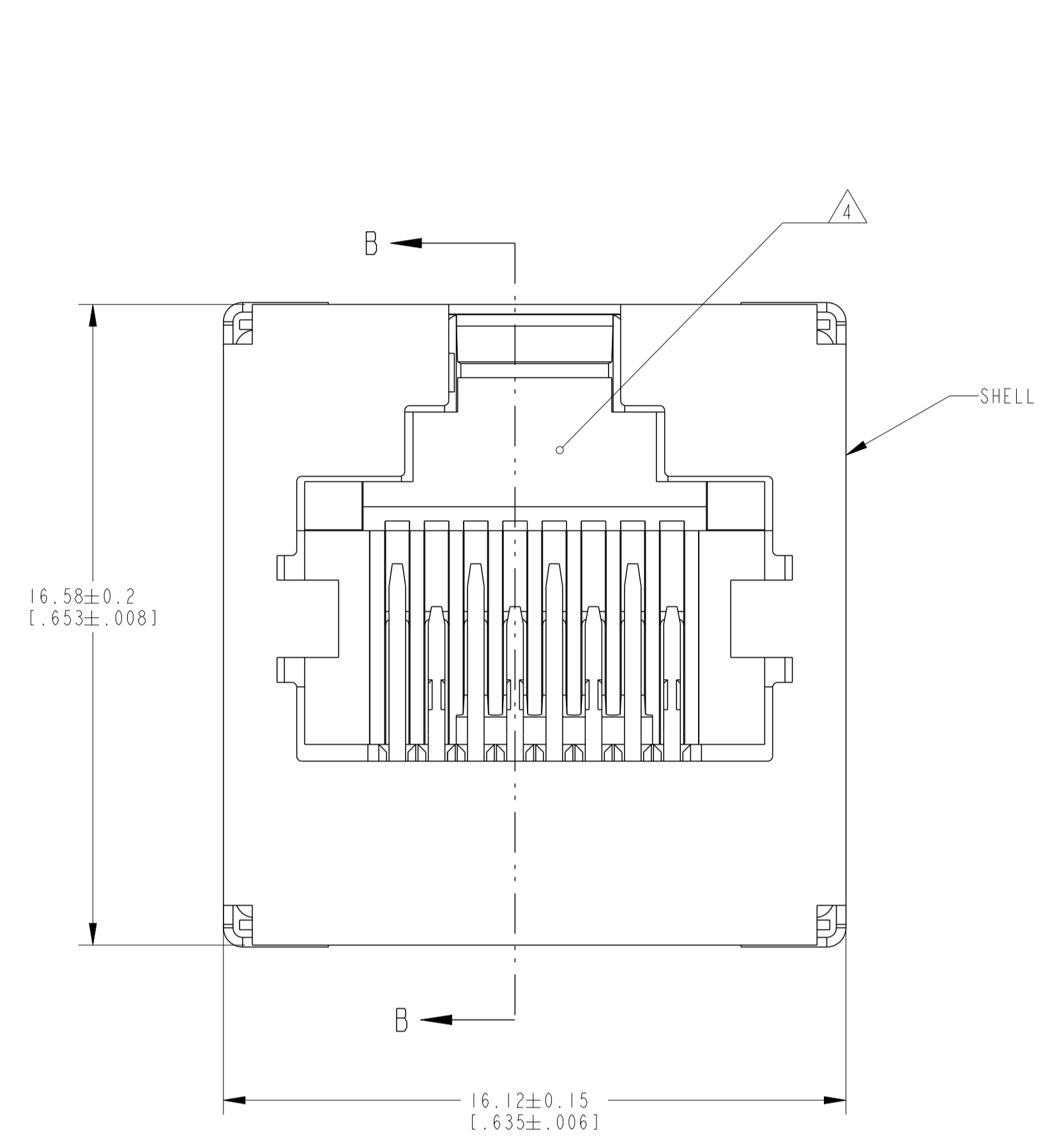
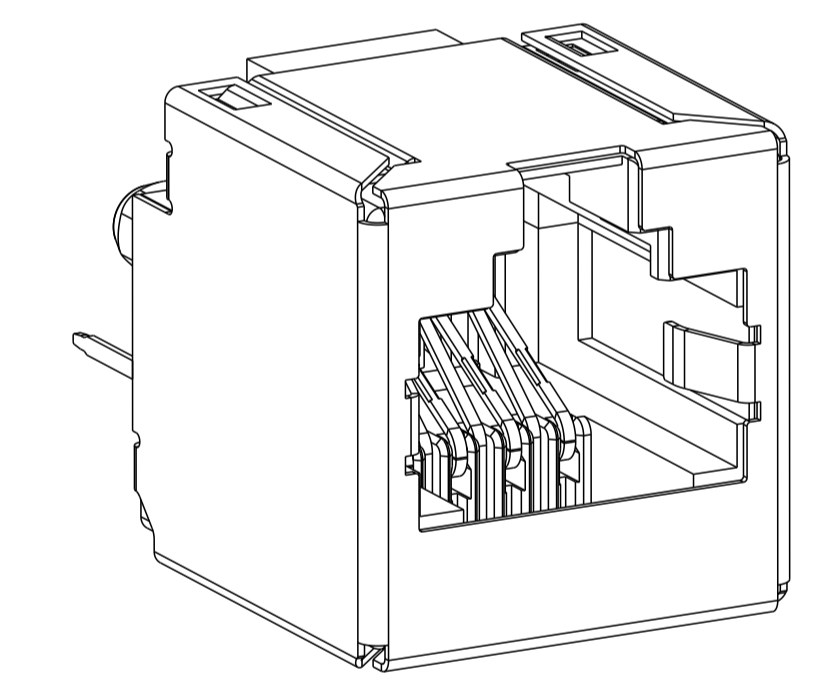
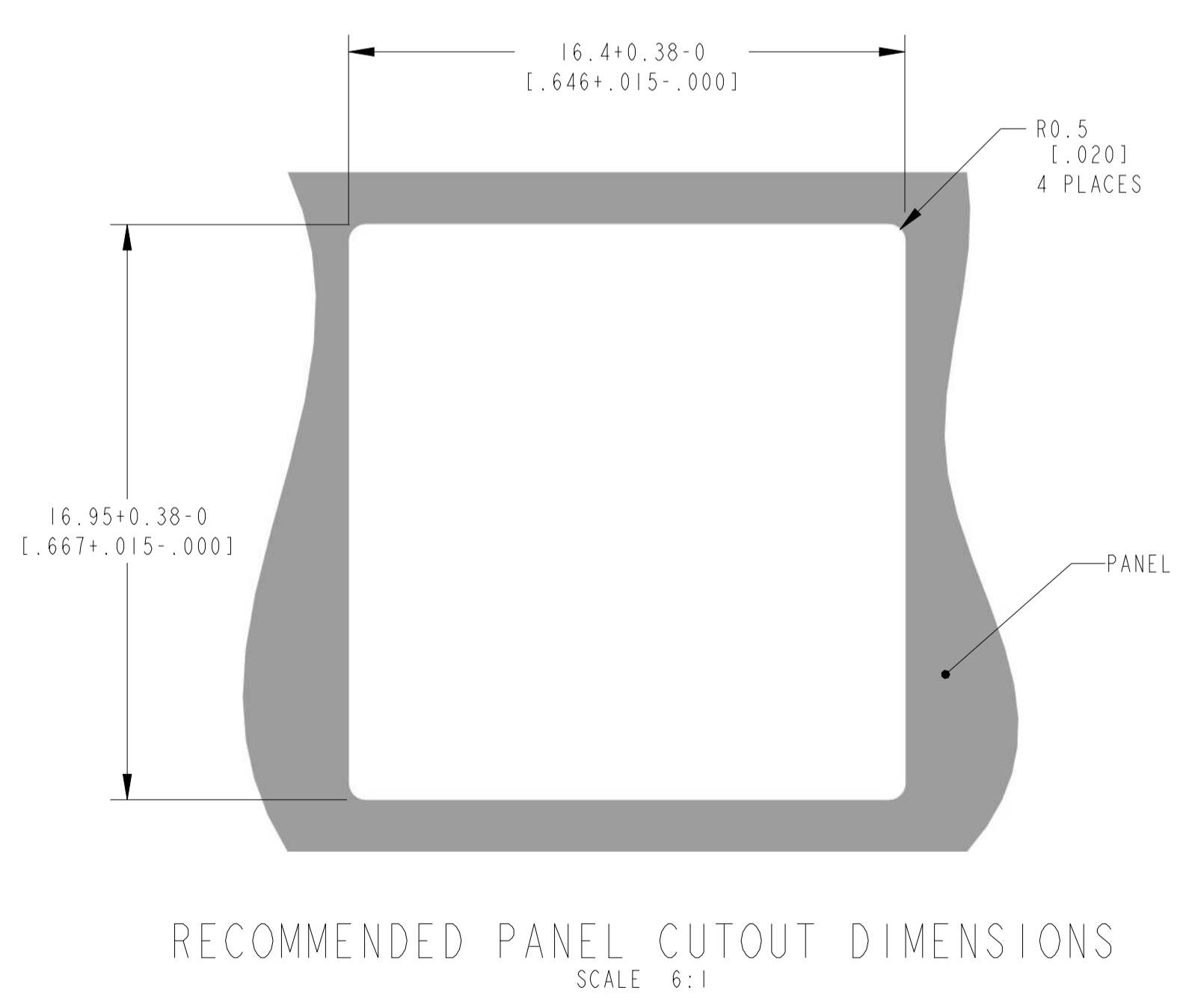
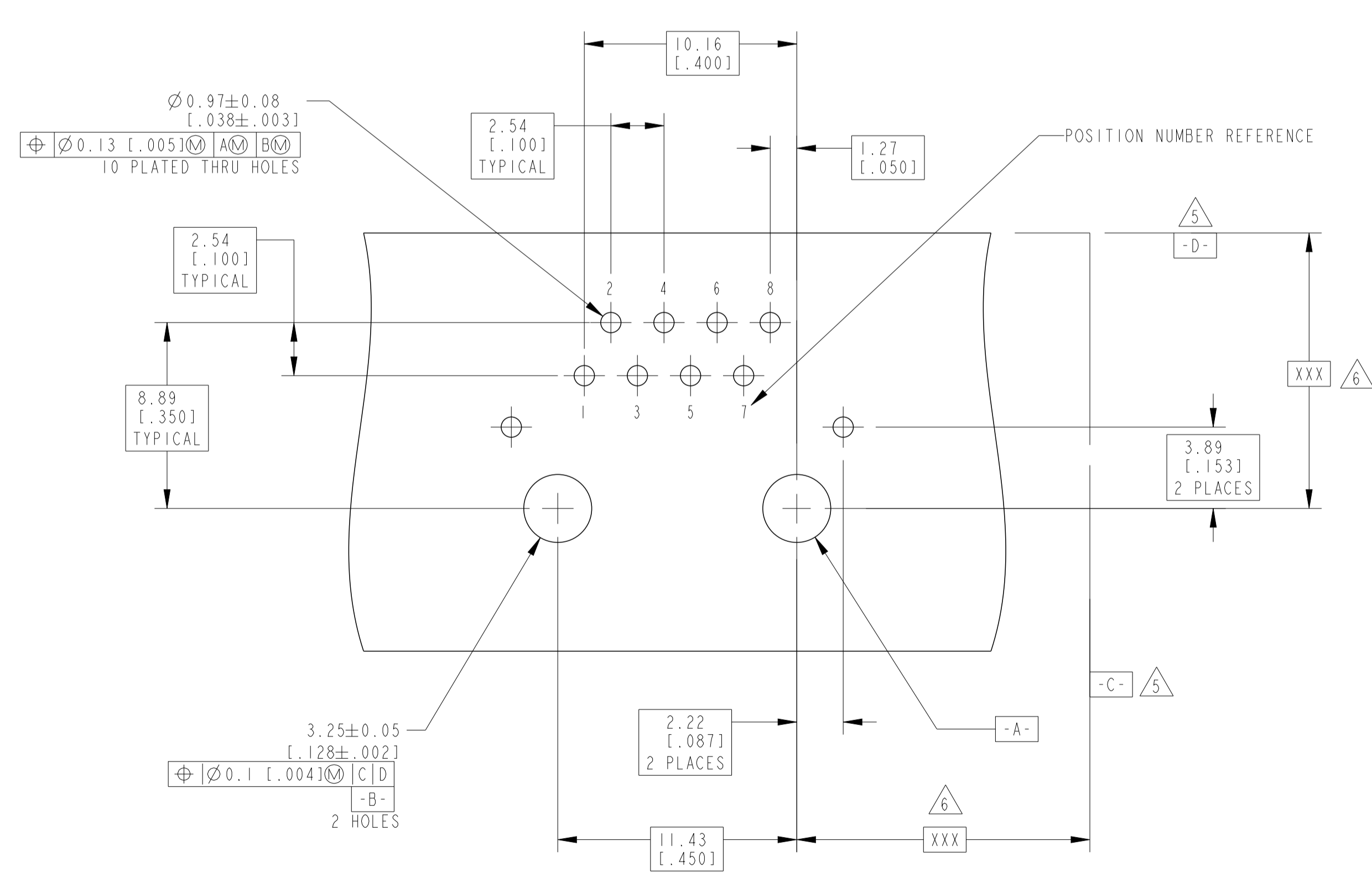


LOC	DIST	REVISIONS					
		P	LTN	DESCRIPTION	DATE	OWN	APVD
AA	22	D		ECO-17-018697	15JAN2018	LL	SH
		E		ECO-18-005131	04APR2018	LL	SH
		E1		REVISED AS PER ECR-23-169440	20APR2023	JK	WH
		E2		REVISED AS PER ECR-23-181524	18JUL2023	JK	JK



- 1 THERMOPLASTIC, COLOR-BLACK
- 2 PHOSPHOR BRONZE
- 3 1.27µm(.000050) MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2µm(.000079) MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27µm(.000050) MIN NICKEL
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F
- 5 DATUMS ESTABLISHED BY CUSTOMER
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER
- 7 COPPER ZINC ALLOY
- 8 PREPLATED WITH 1.27µm(.000050) MIN THICK NICKEL AND HOT TIN DIP ON PCB GROUND TABS
- 9 WITH IMPROVED CHAFMERS ON TERMINAL EDGES.
- 10 WITHOUT COMPENSATORY PLATE
- 11 LOOSE PIECE PN
- 12 1.27µm(.000050) MIN NICKEL PLATED OVERALL AND 2.03µm(.000080) MIN THICK HOT DIP TIN ON PCB GROUND TABS.
- 13 IR REFLOW PROCESS COMPATIBLE.
- 14 PACKED WITH TAPE/REEL.



RECOMMENDED  
PRINTED CIRCUIT BOARD  
LAYOUT  
RECOMMENDED PRINTED CIRCUIT BOARD  
THICKNESS 1.4[.055] MIN  
COMPONENT SIDE OF PRINTED CIRCUIT BOARD

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	OWN V. SLACK/L. A. MAYER CHK J. WESTMAN APVD S. FLICKINGER	DATE 13 JUNE 2005 13 JUNE 2005 13 JUNE 2005
0 PLC ±.3 [0.012]	1 PLC ±0.3 [0.012]	NAME S. FLICKINGER	PRODUCT SPEC
2 PLC ±0.13 [0.005]	3 PLC ±.13 [0.005]	APPLICATION SPEC	108-1163-6
4 PLC ±.	5 PLC ±.	SIZE	114-2158
ANGLES ±.		WEIGHT	
MATERIAL:	HOUSING: 1	FINISH:	SHELL: 8
CONTACTS:	SHELL: 1	CONTACT: 3	

TE Connectivity

MODULAR JACK ASSEMBLY,  
VERTICAL, THRU HOLE,  
SHIELDED, 8 POSITION

SCALE 5:1 SHEET 1 OF 1 REV E2